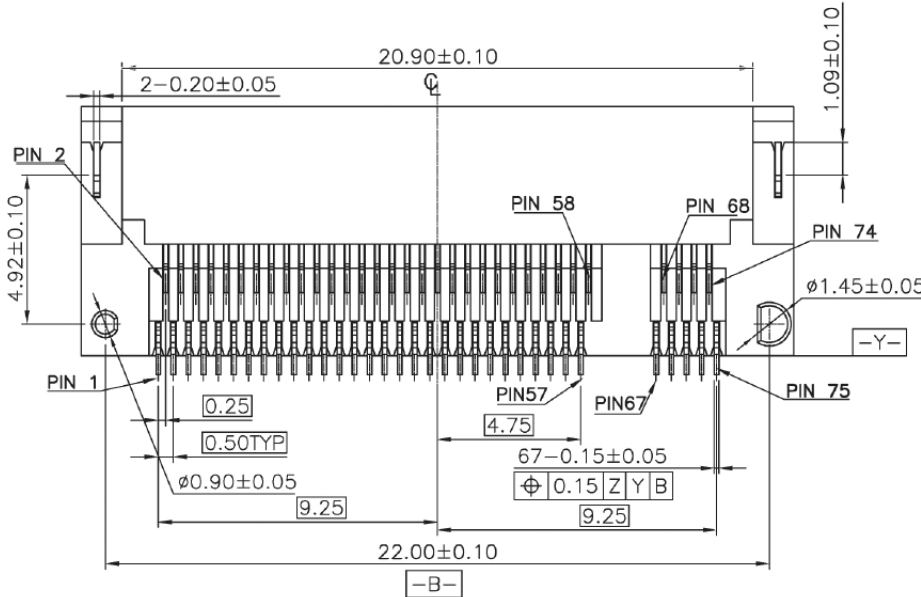
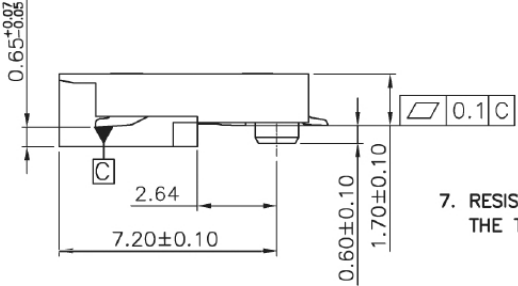
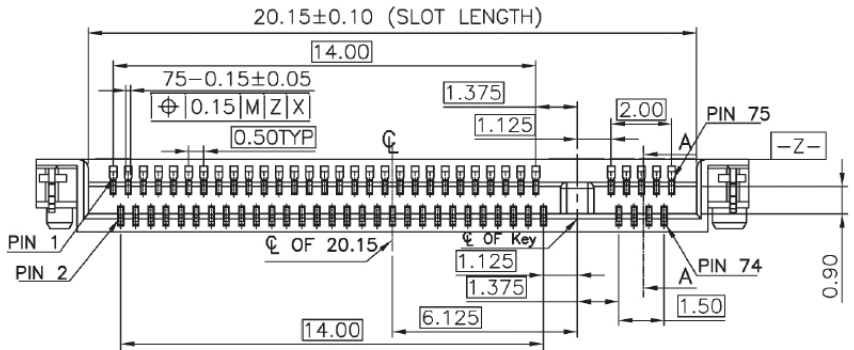


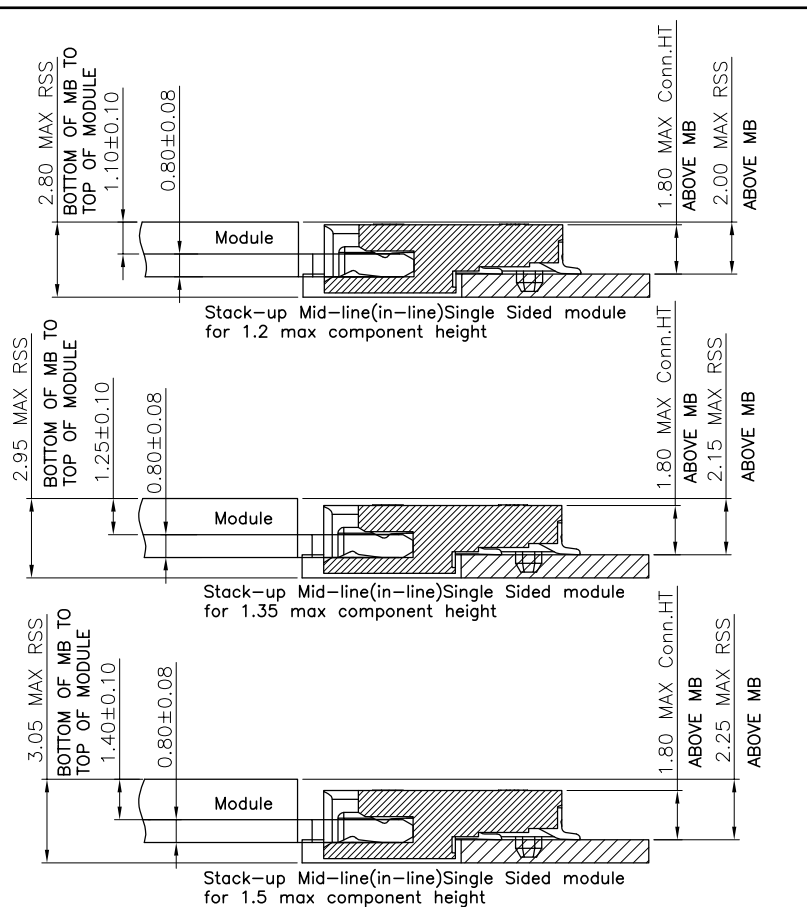
- NOTES:
- MATERIAL SPECIFICATION:
 - 1-1. HOUSING: LCP+40%GF, UL94V-0, COLOR: BLACK.
 - 1-2. CONTACT: COPPER ALLOY C1065.
 - 1-3. SMT TAB: S50C.
 - PLATING SPECIFICATION:
 - 2-1. CONTACT:
 - 50u" MIN. NICKEL UNDER PLATING OVER ALL.
 - G/F PLATING ON SOLDER AREA.
 - GOLD PLATING ON CONTACT AREA: SEE TABLE
 - 2-2. SMT TAB:
 - 50u" MIN. NICKEL UNDER PLATING OVER ALL.
 - 80u" MIN. MATTE TIN PLATING ON SOLDER AREA.
 - HF COMPLIANT.
 - DATE CODE: XXXXXX
 - DAY
 - WEEK
 - YEAR
 - MECHANICAL PERFORMANCE:
 - 5-1. DURABILITY: 25 CYCLES.
 - ELECTRICAL PERFORMANCE:
 - 6-1. CURRENT: 0.5A PER PIN.
 - 6-2. LLCR: INITIAL 55mΩ MAX.; FINAL ΔLLCR=20mΩ MAX..
 - RESISTANCE TO HEAT:
 - THE TEMPERATURE SHALL BE 260±5°C MAINTAINING 10±1 SECONDS.



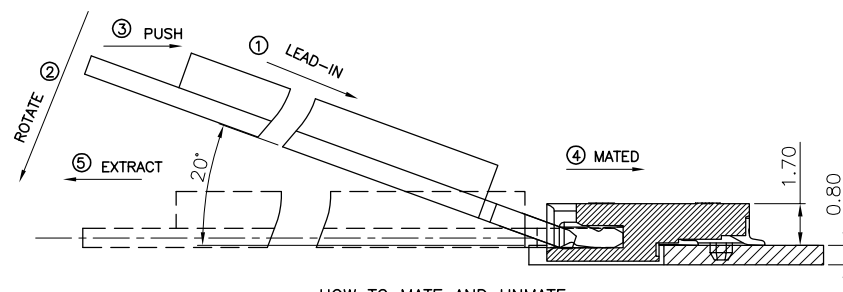
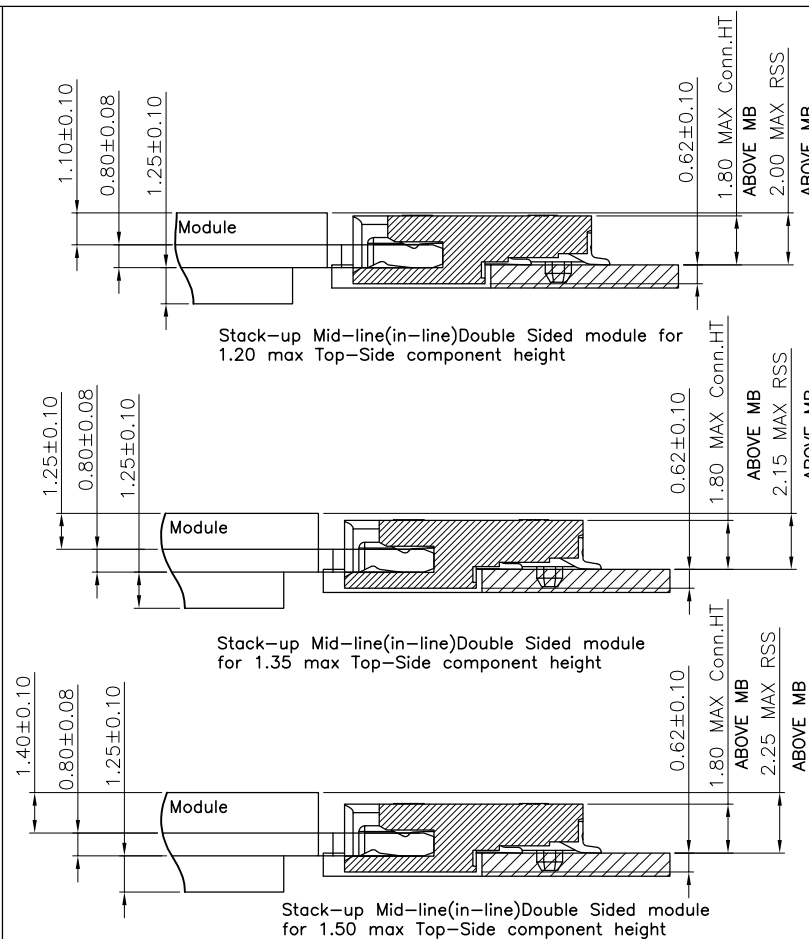
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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5'	DRAWN BY :	DATE :	PART NAME:
	陈一鸣	2014-02-23	NGFF M.2 M KEY 1.8H 0.5PH
UNIT: mm [inch] SCALE:1:1 SIZE: A4	CHECKED BY:	DATE :	PART NO. HYCW44M-05NGFF-180B
	马跃	2014-02-23	MOLD NO.
APPROVED BY: 邱敏	DATE :	DRAW NO. HYC-2405181131	SHEET NO. 1 OF 1
	2014-02-23		

Assembly stack height schematic diagram



Assembly stack height schematic diagram



HOW TO MATE AND UNMATE

MATE: ① → ④

EXTRACT: ⑤

NOTE: Mating force will generate from step 3 to step 4.



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2° X.X° ±0.5°	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NGFF M.2 M KEY 1.8H 0.5PH
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. : HYCW44M-05NGFF-180B
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO. : HYC-2405181131
			SHEET NO. : 1 OF 1

